Texas Instruments

## Bill of Materials

TI DESIGNS PMP9300\_Filter

| Designator     | Quantity | Value | Description                                 | PackageReference | PartNumber          | Manufacturer                                  |
|----------------|----------|-------|---|------------------|---------------------|---|
| C1, C2         | 2        | 0.1uF | 10%, X7R, 0603                              | 0603             | GRM188R72A104KA35D  | MuRata  |
| C4, C5         | 2        | 1.0µF | CAP CER 1UF 50V 10% X7R<br>0805             | 0805             | C2012X7R1H105K125AB | TDK Corporation                               |
| C7             |          |       | CAP, CERM, 10uF, 50V, +/-<br>10%, X7R, 1210 | 1210             | GRM32ER71H106KA12L  | MuRata  |
| J1, J2         | 2        |       | Header, 2mm, 2x1, Tin, TH                   | Header, 2mm, 2x1 | TMM-102-01-T-S      | Samtec  |
| J10, J11, J12, | 4        |       | CONN SMA JACK 50 OHM<br>EDGE MNT            | SMA              |                     | Emerson Network Power<br>Connectivity Johnson |
| L1, L4         | 2        | 100uH | INDUCTOR 100UH 190MA<br>1007 SMD            | 1007             | BRC2518T101K        | Taiyo Yuden                                   |
| L2             | 1        | 4.7uH | INDUCTOR 4.7UH 200MA 20% SMD                | 0805             | LBR2012T4R7M        | Taiyo Yuden                                   |
| L3, L5, L6     | 3        | 4.7uH | INDUCTOR 4.7UH 200MA 20% SMD                |                  | BRC2012T4R7MD       | Taiyo Yuden                                   |

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